



Intelligent Sensing, Monitoring, and Optimization of Advanced Manufacturing Systems

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Message from the Guest Editor

Dear Colleagues,

With the evolution of the modern society, many advanced manufacturing systems have been put forward. At the same time, there is growing sophistication in manufacturing processes and an increase in technical risks. The monitoring, optimization and sensing required for the manufacturing process plays a crucial role in ensuring agility in the manufacturing system, process robustness, efficiency improvement and price reduction. Unlike the monitoring, sensing, and optimization technologies that match traditional manufacturing systems, the rapid development of information systems, computer technology and new material, etc., I would drive the revolution of the above intelligent assistive technologies to accommodate the requirements of advanced manufacturing systems.

For this Special Issue, we invite submissions exploring cutting-edge research and recent advances in the fields of intelligent sensing, monitoring and the optimization of advanced manufacturing systems. Both theoretical and experimental studies are welcome, as well as comprehensive review and survey papers.

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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